end 7a of the via 7. The flange portion 9 covers a portion continuing to the one end 7a of the via 7 out of the wiring layer 3.

IN THE CLAIMS

Please amend Claims 1, 2, and 5 as shown in clean form below.[2]

1. (Twice Amended) A printed wiring board, comprising:

an insulating layer having a first surface, and a second surface located on an opposite side of said first surface;

a plurality of circuit patterns formed by etching metal foils laminated on at least said first surface and said second surface of said insulating layer;

a via formed on said insulating layer, said via having one end opened on said first surface of said insulating layer and an other end closed by a circuit pattern of said plurality of circuit patterns formed on a part of said insulating layer other than said first surface;

a first plating layer having a (1) first portion that covers an inner surface of said via and a circuit pattern of said plurality of circuit patterns that closes said other end of said via and which is exposed within said via, and (2) a second portion that covers a circuit pattern of said plurality of circuit patterns that is on said first surface and which continues to said one end of said via; and

a second plating layer laminated on said first plating layer and electrically connecting a circuit pattern of said plurality of circuit patterns formed on said first surface with said circuit pattern of the plurality of circuit patterns that closes said other end of said via.

[2]A marked-up copy of the amended portion of the claims is attached hereto.

2. (Amended) The printed wiring board according to claim 1, wherein said first plating layer is a groundwork on which said second plating layer is formed, and gives conductivity to the inner surface of said via.

5. (Twice Amended) The printed wiring board according to claim 1, wherein said insulating layer and said plurality of circuit patterns form a laminate, and

one of said plurality of circuit patterns is formed inside insulating layer, is exposed within said via, and is covered by said first plating layer.

Please add new Claims 14-16 as shown below.

14. (New) The printed wiring board of claim 1, wherein the second portion of said first plating layer is a flange portion having a shape that projects over the circuit pattern formed on said first surface from said one end of said via.

15. (New) The printed wiring board of claim 14, wherein the second plating layer has a flange portion laminated on said flange portion of said first plating layer.

16. (New) The printed wiring board of claim 1, wherein each of said plurality of circuit patterns laminated on said first surface has a thick portion outside said via where a circuit pattern thickness is increased, said thick portion being formed by laminating said first plating layer and said second plating layer.